

# EECS251B : Advanced Digital Circuits and Systems

## Lecture 10 – Transistor Models

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Feb. 15, 2022, Reuters

Intel to acquire Tower Semiconductor in \$5.4 bln deal

Intel Corp agreed to acquire Tower Semiconductor Ltd (TSEM.TA) for an enterprise value of \$5.4 billion, the companies said on Tuesday.

Intel will acquire Tower for \$53 per share in cash, the statement added.

# Recap

- FinFET and FDSOI processes deployed now
  - Expected to be replaced by nanosheets
- Lithography and manufacturing restrict design rules
  - Need to be aware of implications on design
  - EuV entering production
- More changes coming: forksheets, buried power rails, chiplets – 2.5D and 3D
  - Plurality of interconnect standards



# MOS Transistor and Gate Delay Models

# Modeling Goals

- Models that traverse design hierarchy
  - Start with transistor models
  - Gate delay models
  - Use models to time the design
  - Modeling variability
- 
- Based on 251A, approach
    - Start simple
    - Increase accuracy, when needed

# Device Models

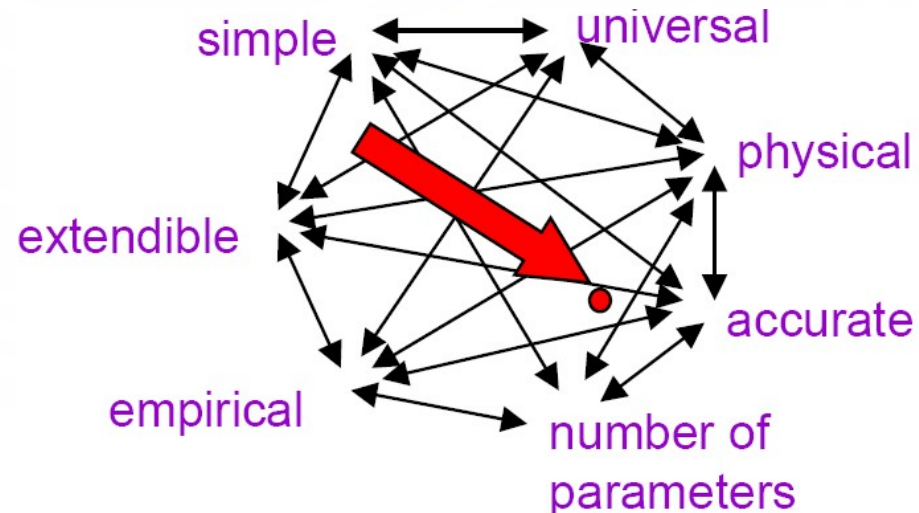
- Transistor models
  - I-V characteristics
  - C-V characteristics
- Interconnect models
  - R, C, L
  - Covered in EE240A

# Transistor Modeling

- Different levels:
  - Hand analysis
  - Computer-aided analysis (e.g. Matlab, Python, Excel,...)
  - Switch-level simulation (some flavors of 'fast Spice')
  - Circuit simulation (Hspice)
- These levels have different requirements in complexity, accuracy and speed of computation
- We are primarily interested in delay and energy modeling, rather than current modeling
- But we have to start from the currents...

# Transistor Modeling

- DC
  - Accurate I-V equations
  - Well behaved conductance for convergence (not necessarily accurate)
- Transient
  - Accurate I-V and Q-V equations
  - Accurate first derivatives for convergence
  - Conductance, as in DC
- Physical vs. empirical



from BSIM group

## Goal for Today

- Develop velocity-saturated model for  $I_{on}$  and apply it to sizing and delay calculation
  - Similar approach as in 251A, just use an analytical model



# Transistor I-V Modeling

- BSIM
  - Superthreshold and subthreshold models
  - Need smoothening between two regions
- EKV/PSP
  - One continuous model based on channel surface potential

# Announcements

- Assignment 1 posted this week
  - No new lab this week
- Project proposals due next Thursday
- No class on Tuesday

# Project proposals

- Title: Pick a meaningful title
- Authors, contact e-mail
- 1/2-page abstract
- 5 references



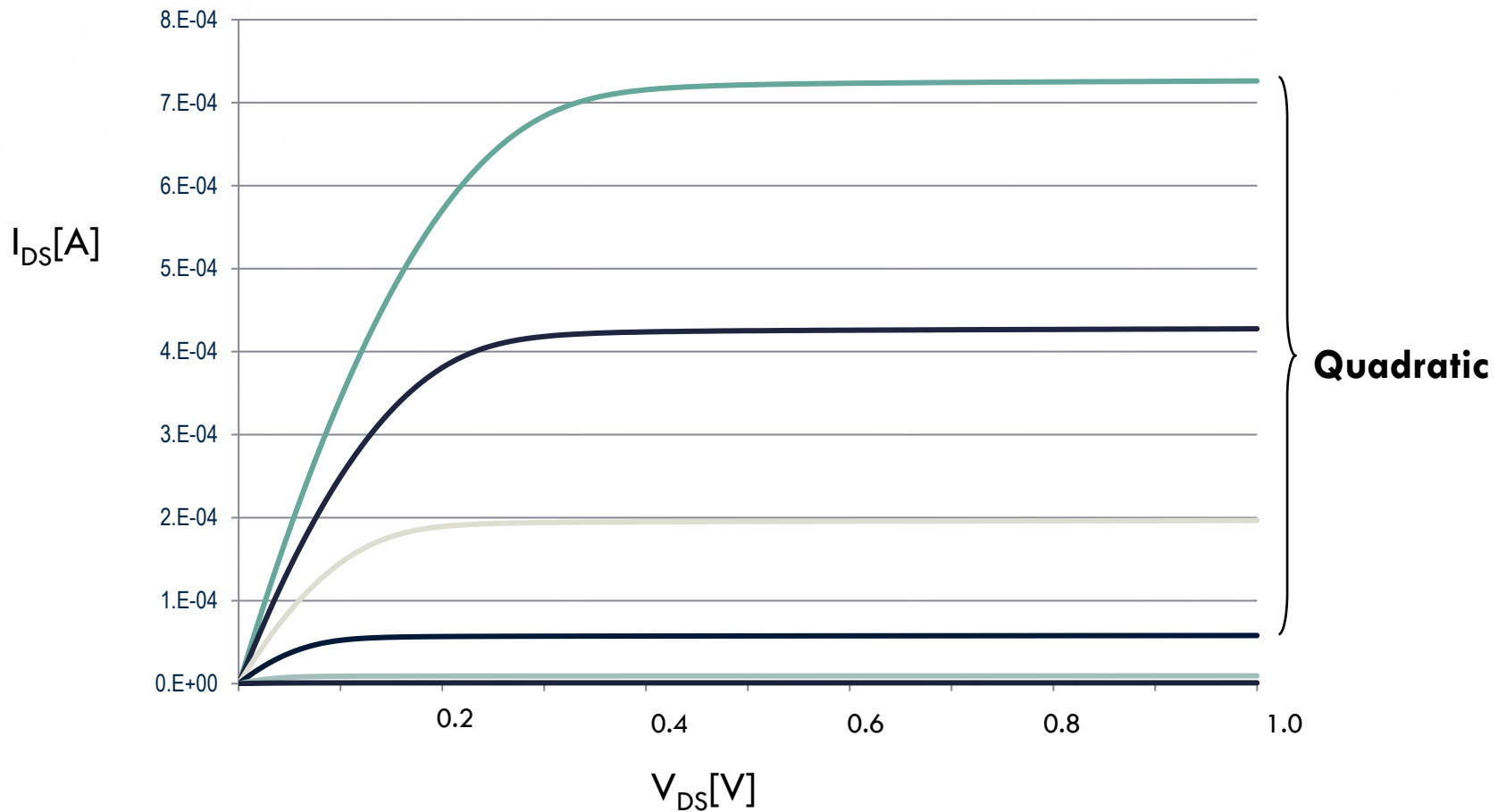
## Long-Channel MOS On-Current

# MOS I-V (BSIM)

Start with the basics:

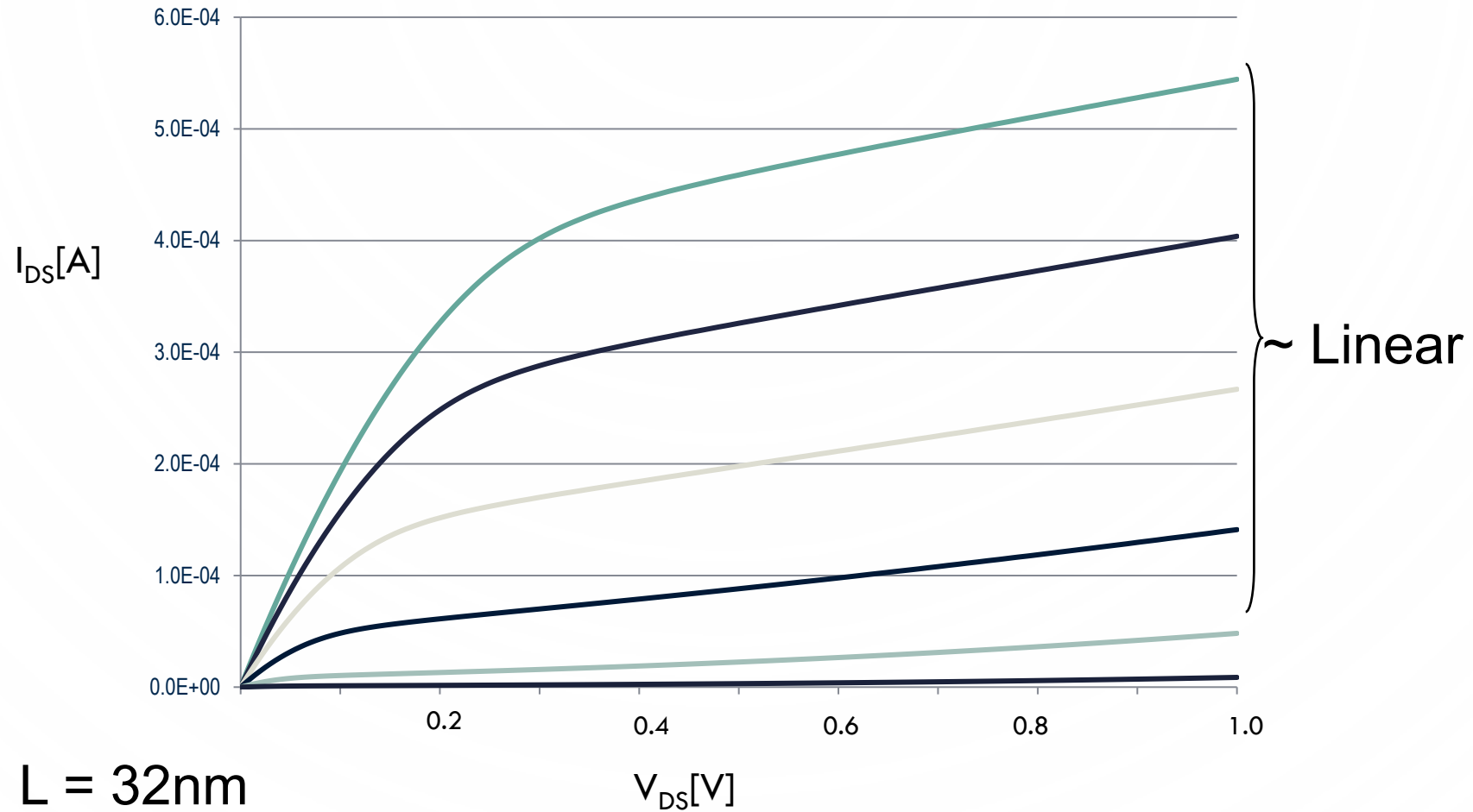
$$I_{DS} = W C_{ox} (V_{GS} - V_{Th} - V_C(x)) \mu E$$

# MOS Currents (32nm CMOS with $L \gg 1\mu\text{m}$ )



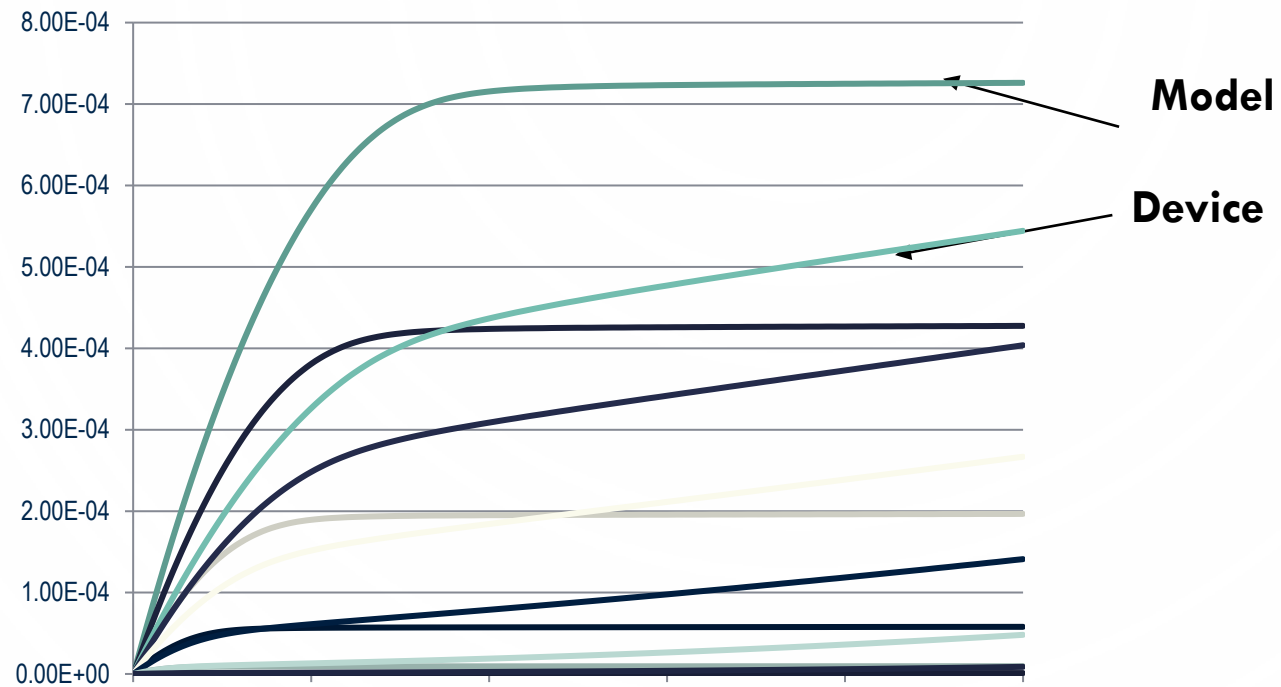
**Currents according to the quadratic model**  
**Correct for long channel devices ( $L \sim \mu\text{m}$ )**

# Simulated 32nm Transistor



L = 32nm

# Simulation vs. Model



Major discrepancies:

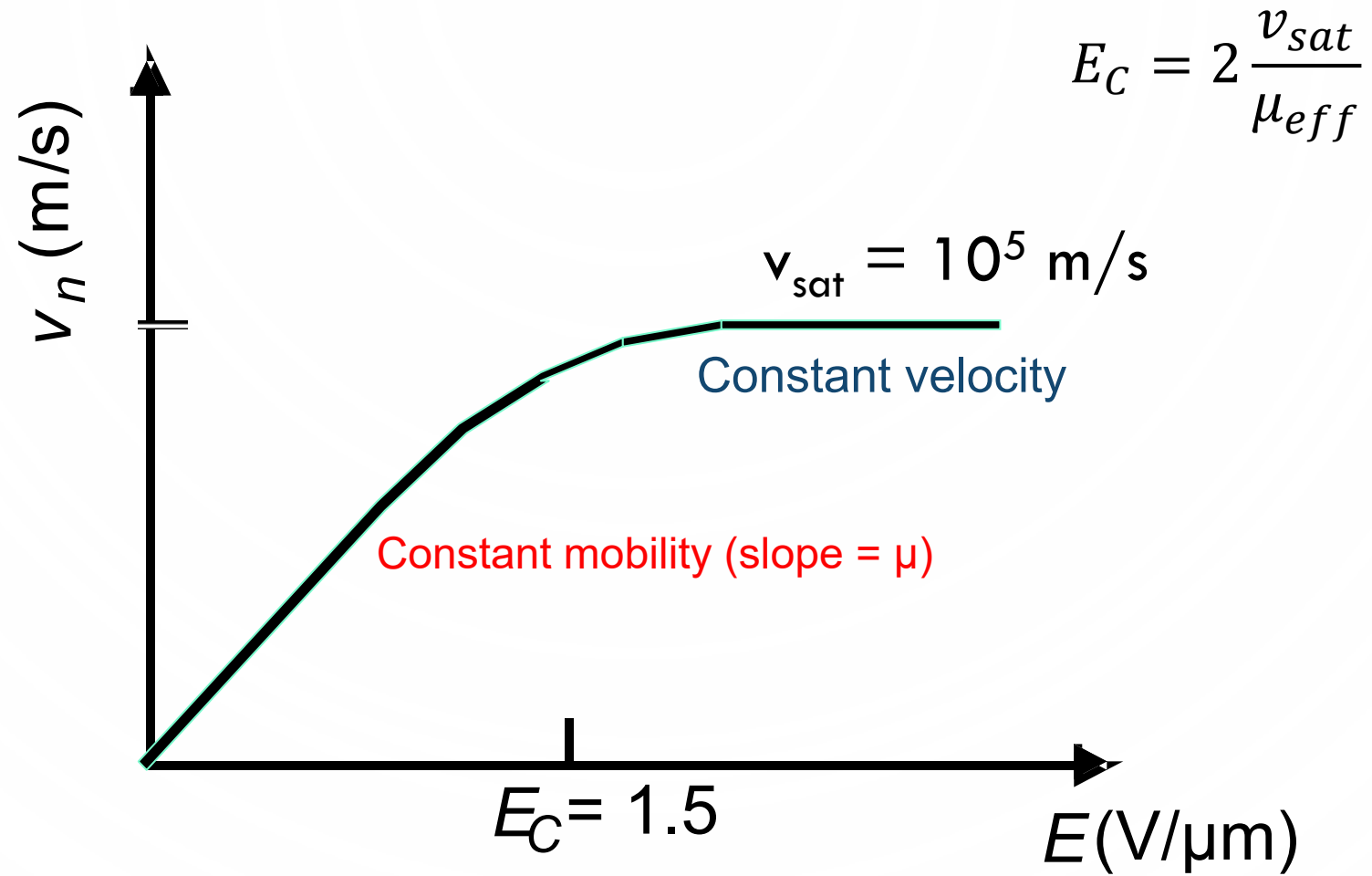
- shape
- saturation points
- output resistances





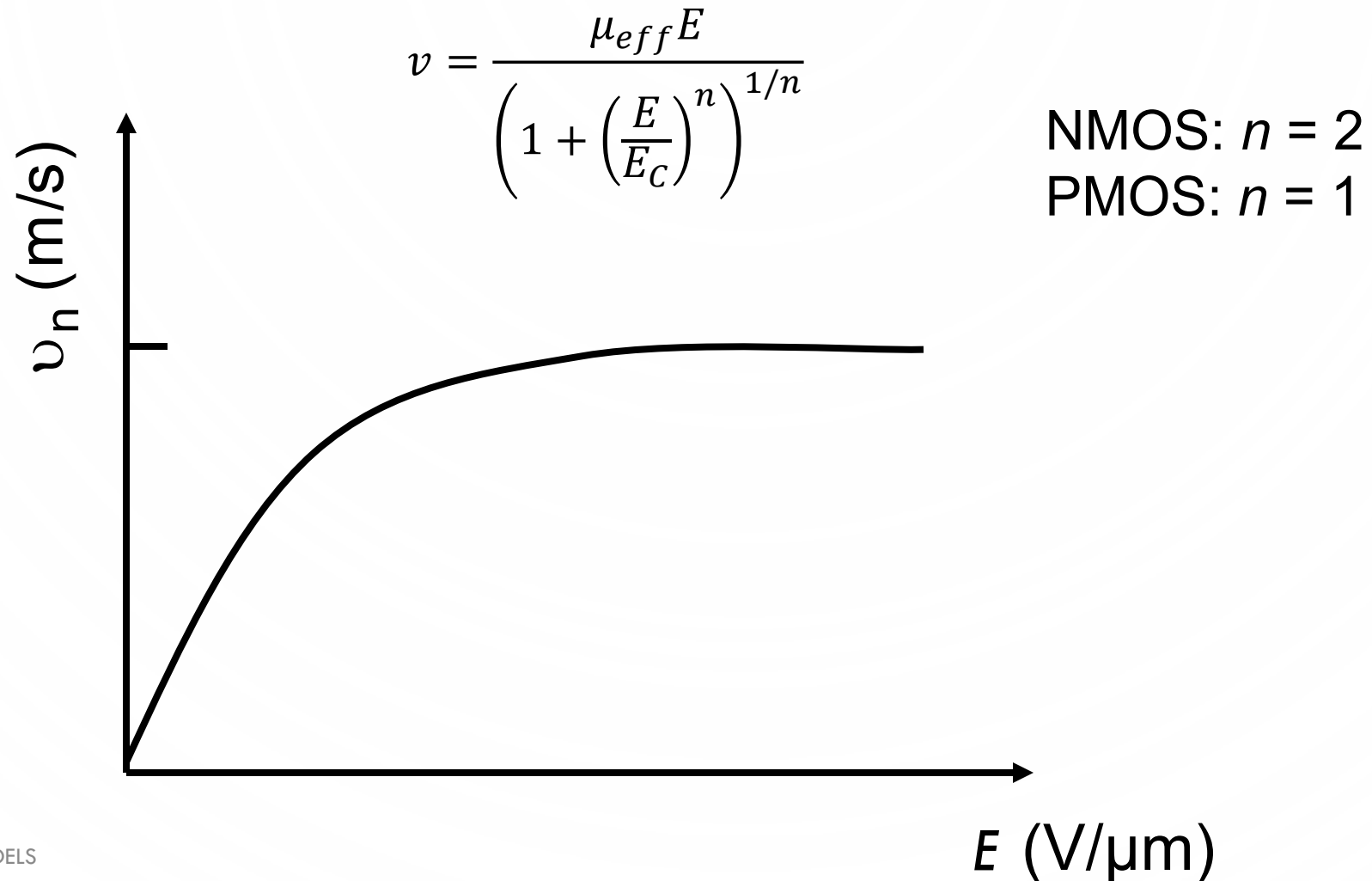
## Velocity Saturation

# Velocity Saturation



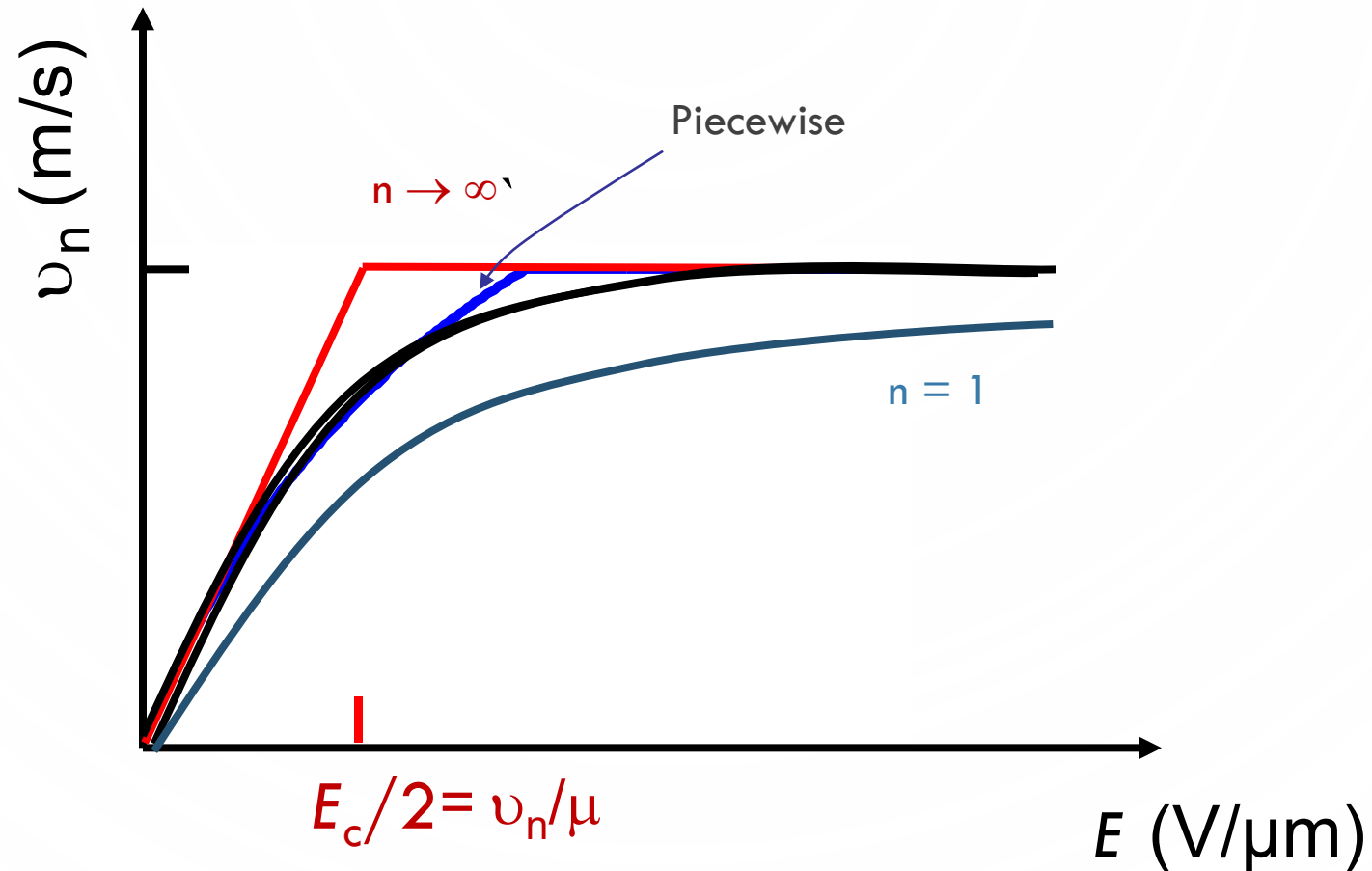
# Modeling Velocity Saturation

- Fit the velocity-dependence curve



# Modeling Velocity Saturation

- A few approximations: (a)  $n \rightarrow \infty$ , (b)  $n = 1$ , (c) piecewise





## Short-Channel MOS On-Current

## Approximation $n \rightarrow \infty$

1)  $v = \mu_{eff} E, \quad E < E_c$

$$I_{DS} = \mu C_{ox} \frac{W}{L} \left( (V_{GS} - V_{Th}) V_{DS} - \frac{V_{DS}^2}{2} \right)$$

2)  $v = v_{sat}, \quad E > E_c$

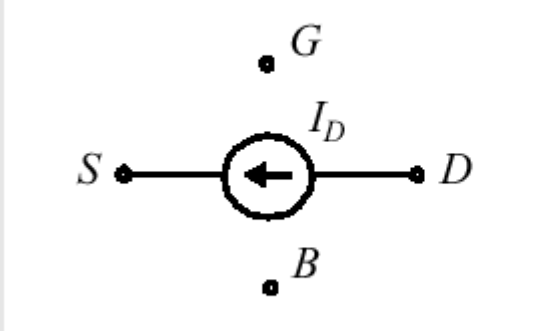
$$I_{Dsat} = \mu C_{ox} \frac{W}{L} \left( (V_{GS} - V_{Th}) V_{Dsat} - \frac{V_{Dsat}^2}{2} \right)$$

$$V_{Dsat} = ?$$

Can be reduced to Rabaey D1C model by making  $V_{Dsat} = \text{const}$

Is this physically justified?

# MOS Model from DIC, 2<sup>nd</sup> ed.



$$I_D = 0 \text{ for } V_{GT} \leq 0$$

$$I_D = k' \frac{W}{L} \left( V_{GT} V_{min} - \frac{V_{min}^2}{2} \right) (1 + \lambda V_{DS}) \text{ for } V_{GT} \geq 0$$

$$\text{with } V_{min} = \min(V_{GT}, V_{DS}, V_{DSAT}),$$

$$V_{GT} = V_{GS} - V_T,$$

$$\text{and } V_T = V_{T0} + \gamma (\sqrt{|-2\phi_F + V_{SB}|} - \sqrt{|-2\phi_F|})$$

$\gamma$  - body effect parameter

From Rabaey, 2<sup>nd</sup> ed.

# Unified MOS Model

- Model presented is compact and suitable for hand analysis.
- Still have to keep in mind the main approximation: that  $V_{DSat}$  is constant .

When is it going to cause largest errors?

- When does  $E$  scale? – Transistor stacks.
- But the model still works fairly well.
  - Except for stacks



# Approximation $n = 1$ , piecewise

- $n = 1$  is solvable, piecewise closely approximates

Velocity,  $v$ :

$$v = \begin{cases} \frac{\mu_{eff} E}{1 + E/E_C}, & E < E_C = \frac{2v_{sat}}{\mu_{eff}} \\ v_{sat}, & E > E_C \end{cases}$$

Sodini, Ko, Moll, TED'84  
Toh, Ko, Meyer, JSSC'88  
BSIM model

# Drain Current

- We can find the drain current by integrating  $I_{DS}$

$$I_{DS} = W C_{ox} (V_{GS} - V_{Th} - V_C(x)) v$$

Linear:

$$I_{DS} = \frac{\mu C_{ox}}{1 + (V_{DS}/E_C L)} \frac{W}{L} \left( (V_{GS} - V_{Th}) V_{DS} - \frac{V_{DS}^2}{2} \right)$$

In saturation:

$$I_{DSat} = C_{ox} W v_{sat} (V_{GS} - V_{Th} - V_{DSat})$$

$$I_{DSat} = \frac{\mu C_{ox}}{1 + (V_{DSat}/E_C L)} \frac{W}{L} \left( (V_{GS} - V_{Th}) V_{DSat} - \frac{V_{DSat}^2}{2} \right)$$

# Drain Current in Velocity Saturation

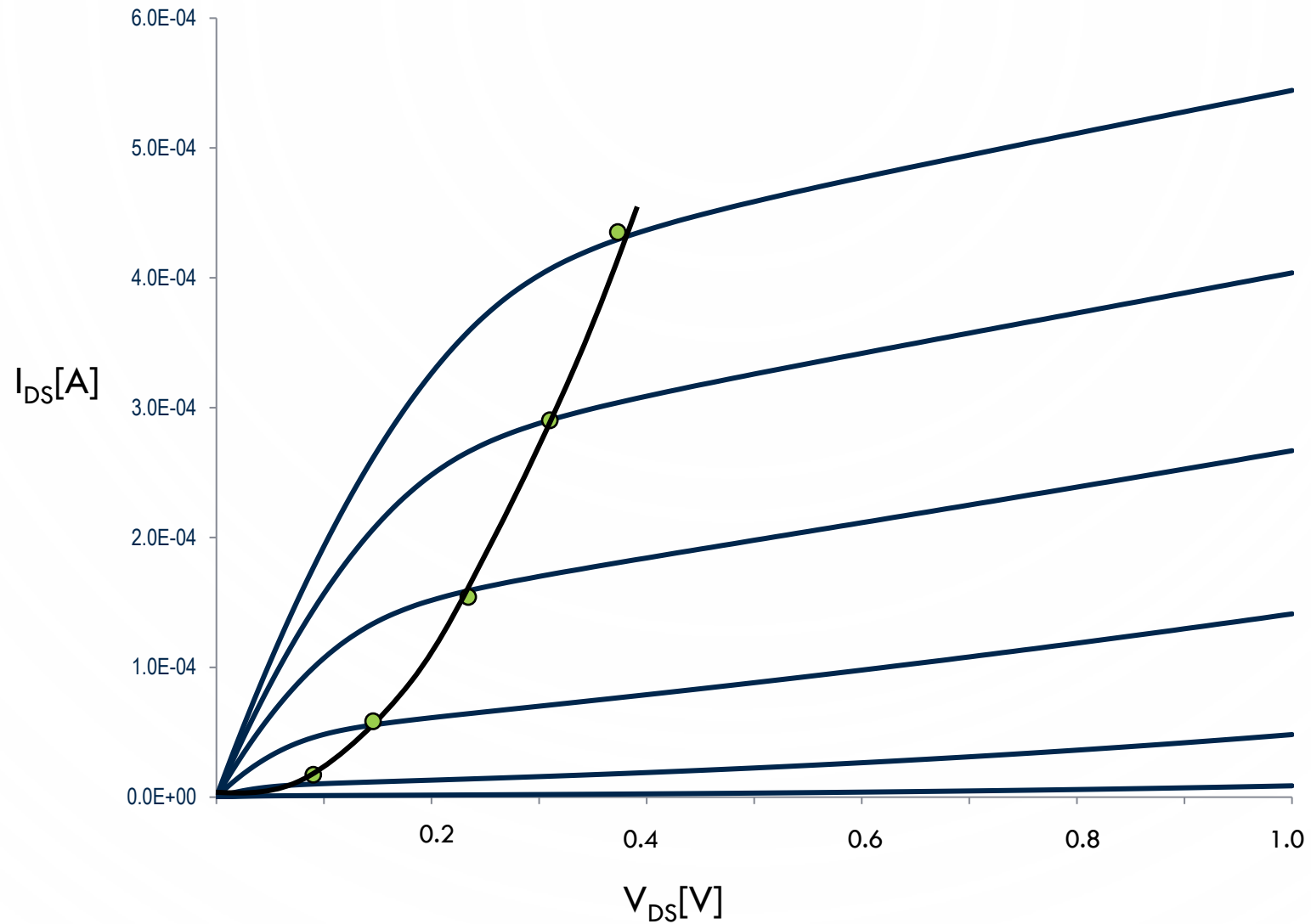
- Solving for  $V_{Dsat}$

$$V_{DSat} = \frac{(V_{GS} - V_{Th})E_C L}{(V_{GS} - V_{Th}) + E_C L}$$

- And saturation current

$$I_{DSat} = \frac{W}{L} \frac{\mu_{eff} C_{ox} E_C L}{2} \frac{(V_{GS} - V_{Th})^2}{(V_{GS} - V_{Th}) + E_C L}$$

# Velocity Saturation



# Velocity Saturation

- $E_C L$  is  $V_{GS}$ -dependent
- Can calculate  $V_{DSat}$  ( $V_{Th} \sim 0.4V$  in 28nm)

$V_{GS}$ [V]	0.5	0.6	0.7	0.8	0.9	1.0
$V_{DSat}$ [V]	0	0.05	0.11	0.18	0.25	0.33

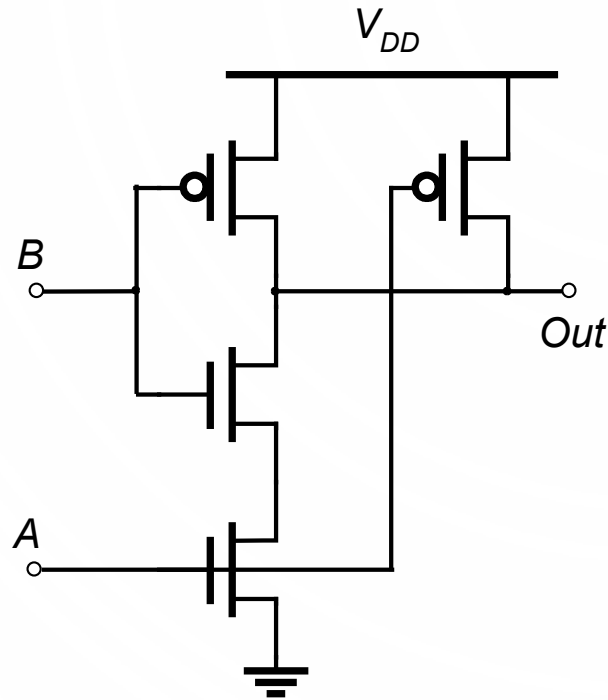
- For  $V_{GS} - V_{Th} \ll E_C L$ ,  $V_{DSat}$  is close to  $V_{GS} - V_{Th}$
- For large  $V_{GS}$ ,  $V_{DSat}$  bends upwards toward  $E_C L$
- Therefore,  $E_C L$  can be sometimes approximated with a constant term
  - But also need to understand the limitation of the approximation



## Application of I-V Models

# Application of Models: NAND Gate

- 2-input NAND gate

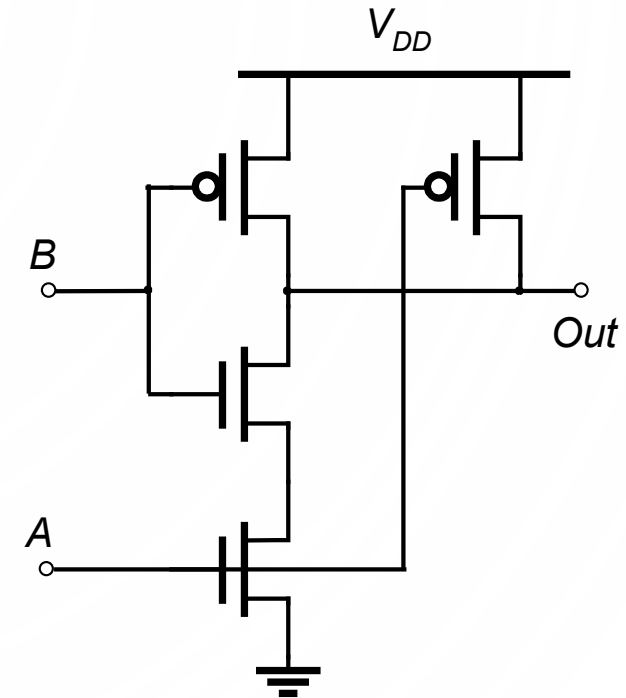


Sizing for equal transistions:

- P/N ratio ( $\beta$ -ratio): 1 for  $L < 20\text{nm}$ , 1.6 for  $20\text{nm} < L < \sim 65\text{nm}$ , 2 for  $L > 90\text{nm}$
- Upsizing stacks by a factor proportional to the stack height

# Transistor Stacks

- With transistor stacks,  $V_{DS}$ ,  $V_{GS}$  reduce.
- Unified model assumes  $V_{DSat} = \text{const.}$
- For a stack of two, appears that both have exactly double  $R_{ekv}$  of an inverter with the same width
- Therefore, doubling the size of each, should make the pull-down  $R$  equivalent to an inverter





# Velocity Saturation

- As  $(V_{GS}-V_{Th})/E_C L$  changes, the depth of saturation changes

$$I_{DSat} = \frac{W}{L} \frac{\mu_{eff} C_{ox} E_C L}{2} \frac{(V_{GS} - V_{Th})^2}{(V_{GS} - V_{Th}) + E_C L}$$

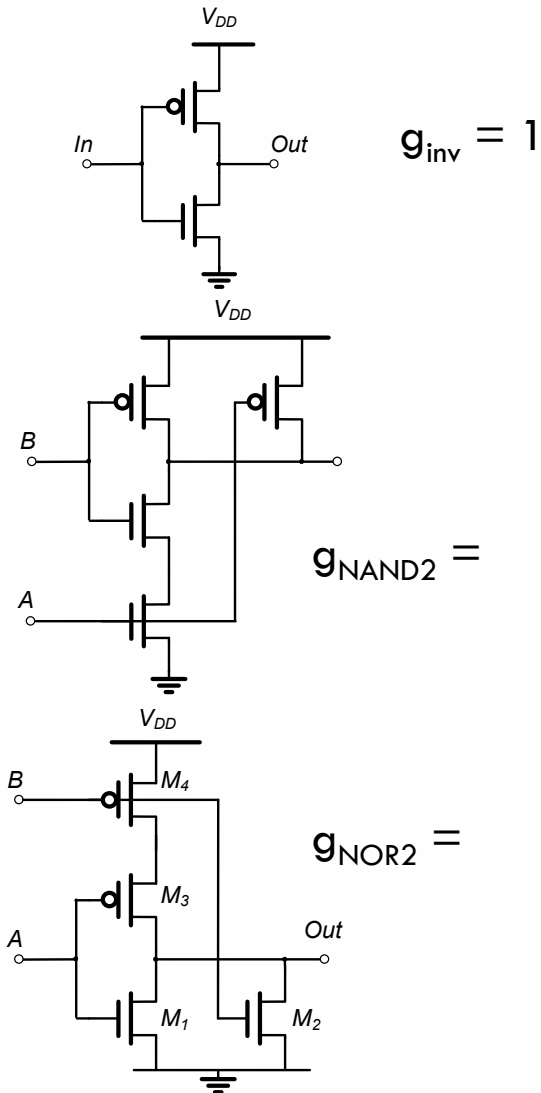
- For  $V_{GS}, V_{DS} = 1.0V$ ,  $E_C L$  is  $\sim 0.75V$
- With double length,  $E_C L$  is  $1.5V$  (in this model in 28nm)
- Stacked transistors are less saturated
- $V_{GS}-V_{Th} = 0.6V$ ,  $I_{DSat} \sim 2/3$  of inverter  $I_{DSat}$  (64%)
- Therefore NAND2 should have pull-down sized 1.5X
- Check any library NAND2's
- Current halved in a stack of 3

## Note about FinFETs

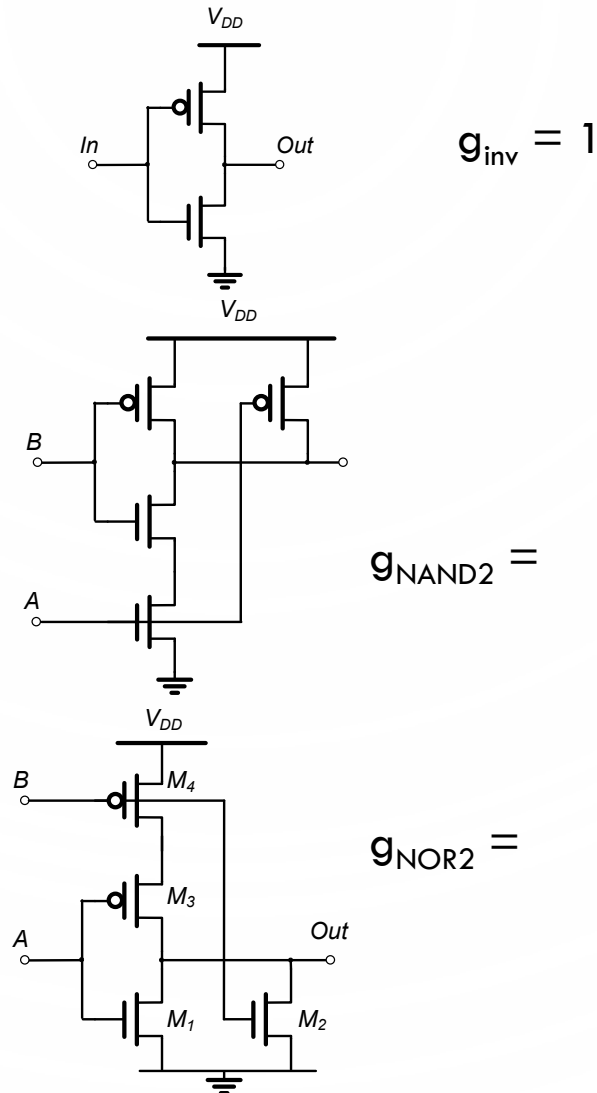
- Widths are quantized

# Example: Logical Effort

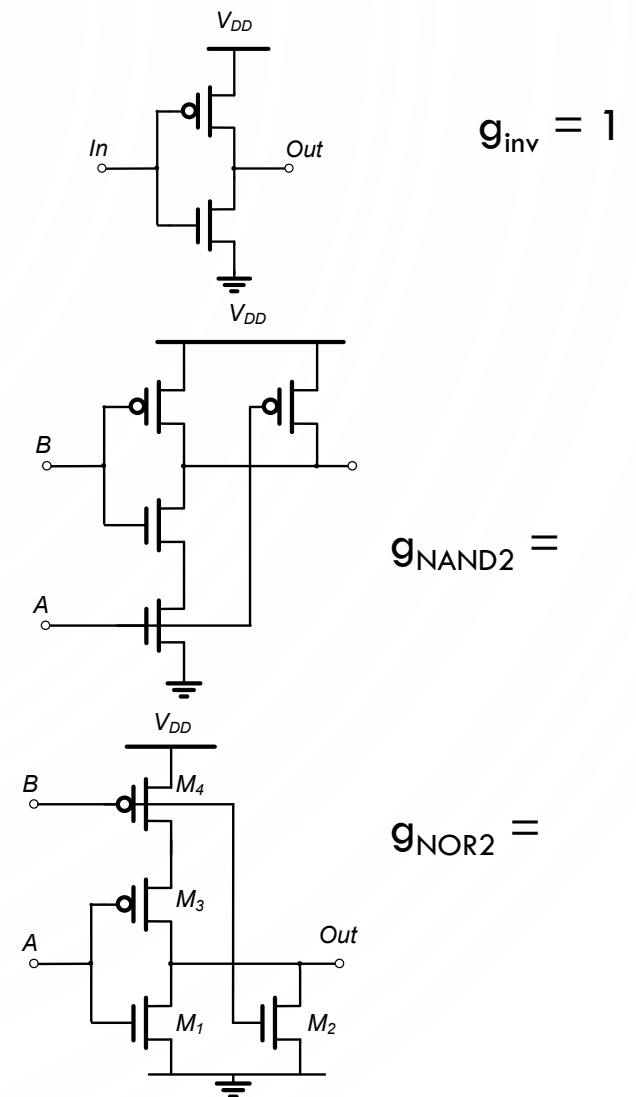
- Older CMOS (>90nm)



- Planar CMOS (~28nm, bulk, FDSOI)



- FinFET (7nm)





## Other Velocity Saturation Models

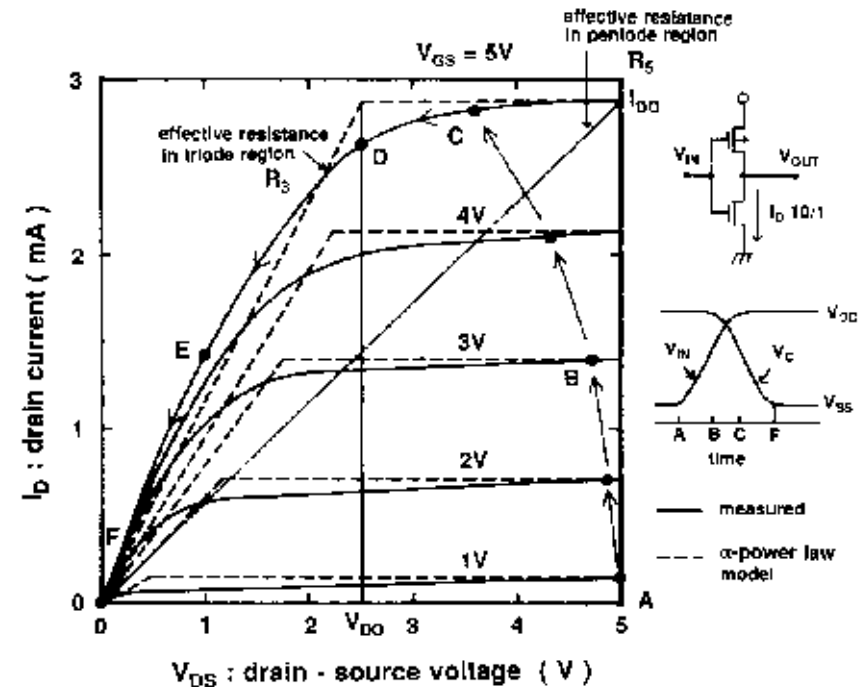
# Other Models: Alpha Power Law Model

- Simple model, sometimes useful for hand analysis

$$I_{DS} = \frac{W}{2L} \mu C_{ox} (V_{GS} - V_{Th})^\alpha$$

Parameter  $\alpha$  is between 1 and 2.

Sakurai, Newton, JSSC 4/90

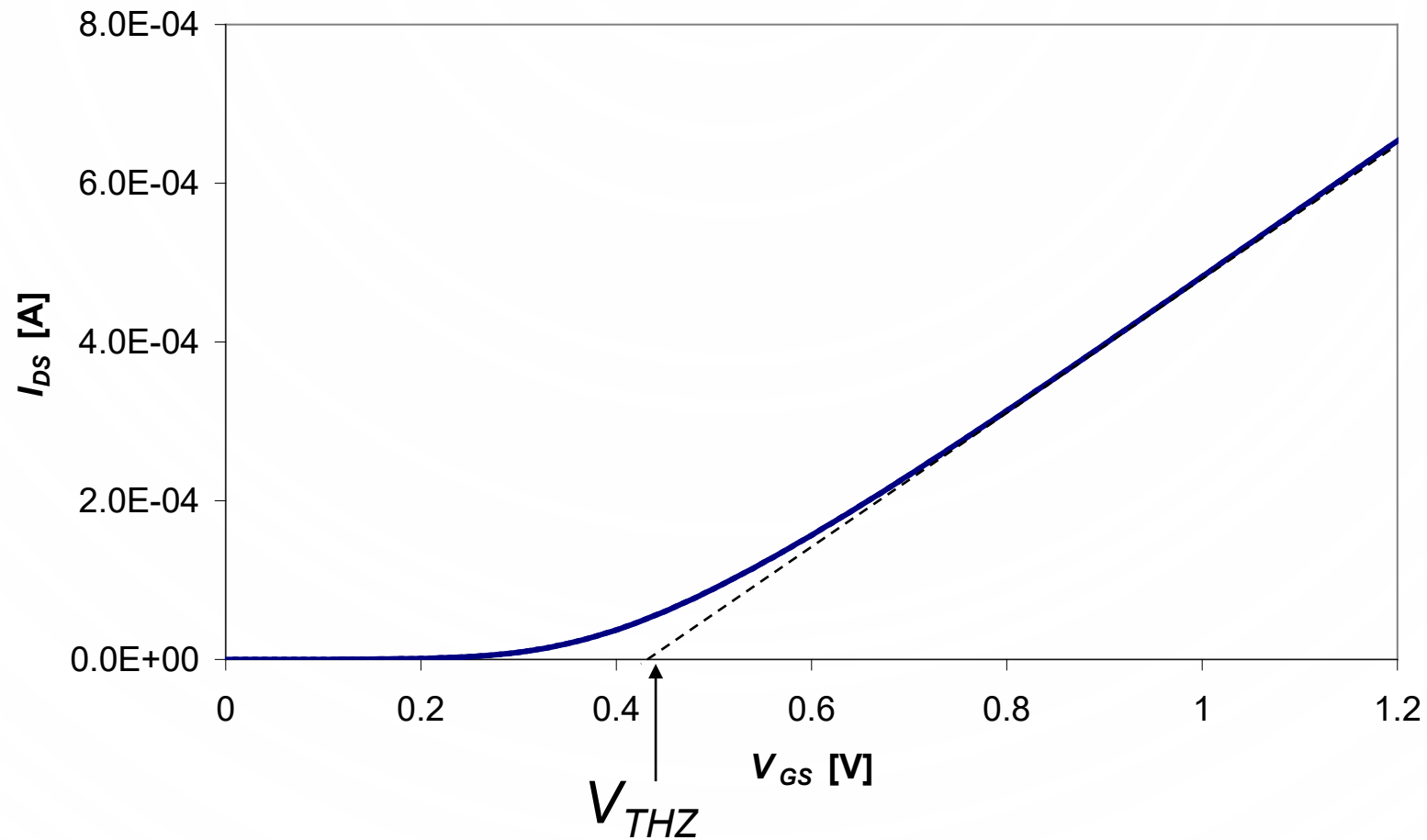


# Alpha Power Law Model

- This is not a physical model
- Simply empirical:
  - Can fit (in minimum mean squares sense) to variety of  $\alpha$ 's,  $V_{Th}$
  - Need to find one with minimum square error – fitted  $V_{Th}$  can be different from physical
  - Can also fit to  $\alpha = 1$ 
    - What is  $V_{Th}$ ?

# $K(V_{GS} - V_{THZ})$ Model ( $\alpha = 1$ )

Drain current vs. gate-source voltage



# Saturation Current Models

Model	Usage
$I_{DS} = K \frac{W}{L} (V_{GS} - V_{THZ})$	Delay estimates with $V_{DD} \gg V_{TH}$
$I_{DS} = \frac{W}{L} \frac{\mu C_{ox}}{2} (V_{GS} - V_{TH})^2$	Long channel devices (rare in digital)
$I_{DS} = \frac{W}{L} \frac{\mu C_{ox}}{2} (V_{GS} - V_{TH})^\alpha$	Delay estimates in a wider range of $V_{DD}$ 's
$I_{DS} = \frac{W}{L} \mu C_{ox} \left( (V_{GS} - V_{TH}) V_{Dsat} - \frac{V_{Dsat}^2}{2} \right)$	Easy to remember, does not handle stacks correctly
$I_{DS} = \frac{W}{L} \frac{\mu C_{ox}}{2} \frac{E_C L (V_{GS} - V_{TH})^2}{(V_{GS} - V_{TH}) + E_C L}$	Handles stacks correctly, sizing



## Next Lecture

- Delay models